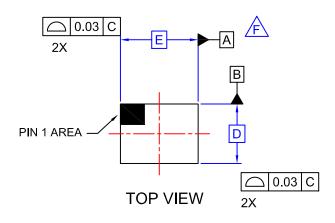
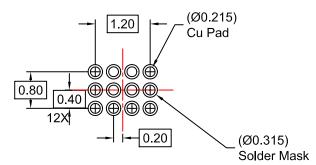
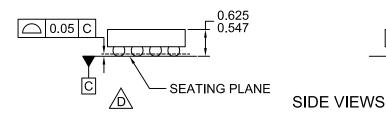
WLCSP12 1.288x1.828x0.586 CASE 567QX ISSUE O

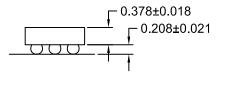
DATE 31 OCT 2016

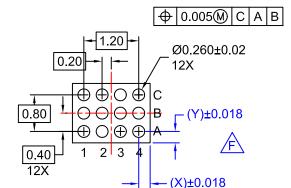




RECOMMENDED LAND PATTERN (NSMD PAD TYPE)







BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

E.PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).

FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

DOCUMENT NUMBER:	98AON13356G	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	, ,
DESCRIPTION:	WLCSP12 1.288x1.828x0.586		PAGE 1 OF 1

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